

ZXFV201, ZXFV202, ZXFV203, ZXFV204 Quad, single, triple and dual video amplifiers

Device description

The ZXFV201, ZXFV202, ZXFV203 and ZXFV204 are quad, single, triple and dual, respectively, high speed amplifiers designed for video and other high speed applications.

Their low differential gain and phase performance make them ideal for video amplifier buffer applications.

The quad allows one IC to drive RGBS format component video signals, while the triple provides RGB component video buffer/driver. The dual amplifier is a mainstay of the video market providing two channels in the space of 1 single in SO8. The small size of the ZXFV202 in SOT23 allows it to be placed where needed for position/size critical applications.

Together with high output drive and slew rate capability, they bring high performance to video applications.

Ordering information

Part number	Descrip- tion	Status	Reel size (inches)	Qty.	Part mark
ZXFV202E5TA	Single	Active	7	3,000	V202
ZXFV202E5TD	Single	Obsolete	7	500	V202
ZXFV202N8TA	Single	Obsolete	7	500	ZXFV202
ZXFV204N8TA	Dual	Obsolete	7	500	ZXFV204
ZXFV204N8TC	Dual	Active	13	2,500	ZXFV204
ZXFV203N14TA	Triple	Active	7	500	ZXFV203
ZXFV203N14TC	Triple	Obsolete	13	2,500	ZXFV203
ZXFV201N14TA	Quad	LTB	7	500	ZXFV201
ZXFV201N14TC	Quad	Obsolete	13	2,500	ZXFV201

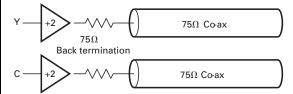
Features

- · High speed
- Gain of 1 3dB bandwidth 210MHz
- Slew rate 380V/μs
- · Good video
- 25 MHz 0.1dB bandwidth
- Differential gain 0.04%
- Differential phase 0.04°
- 40mA output current @ 3V Output
- · Characterized up to 300pF load
- · ±5 Volt supply operation
- Supply current 7.5mA per amplifier

Applications

- Industry standard pinouts
- · Video gain stages
- · CCTV buffer
- · Video distribution
- RGB buffering
- · Home theater
- High speed ADC signal input drive
- Cable driving

Application diagram



Dual amplifier S - video driver

Absolute maximum ratings over operating free-air temperature (unless otherwise stated (a))

Supply voltage (V_{S+} to V_{S-}) -0.5V to +11V

Input voltage (V_{IN-}, V_{IN+}) (b) V_{S-} -0.5V to V_{S+} +0.5 V

Differential input voltage (V_{ID}) $\pm 3V$ Inverting input current (I_{IN-}) (c) $\pm 5mA$ Output current (continuous, $T_J < 110^{\circ}C$) $\pm 60mA$

Internal power dissipation See power dissipation derating table

Storage temperature range -65°C to +150°C

Operating ambient junction temperature (T_{JMAX}) 150°C

NOTES:

(a) Stresses above those listed under Absolute maximum ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

(b) During power-up and power-down, these voltage ratings require that signals be applied only when the power supply is connected.

(c) At high closed loop gains and low gain setting resistors care must be taken if large input signals are applied to the device which cause the output stage to saturate for extended periods of time.

Power derating table

Package	Theta-ja	Power rating at 25'C
SOT23-5	195°C/W	0.64W
SO8	168°C/W	0.74W
SO14	120°C/W	1.04W

Recommended operating conditions

Paramete	7	Min.	Max.	Unit
$V_{S\pm}$	Dual supply voltage range	±4.75	±5.25	V
V _{CMR}	Common mode input voltage range	-3	+3	V
T _A	Ambient temperature range	-40	85	°C

Recommended resistor values

$V_{S\pm}$ = 5V, C_L = 10pF

G _{CL}	R _F	R_G	Peaking
	680		2 dB
1	820	n/c	0
	1000		-2dB
	430	430	2dB
2	470	470	1.5dB
	560	560	0

DC electrical characteristics (±5V power supplies, T_{amb} = 25°C unless otherwise stated. R_f = 1k Ω , R_L = 150 Ω , C_L \leq = 10pF)

Parameter	Conditions	Test	Min.	Тур.	Max.	Unit
Supply voltage V+ operating range			4.75	5	5.25	V
Supply voltage V- operating range			-5.25	-5	-4.75	V
Supply current/per channel		Р	5.0	7.5	10	mA
Input common mode voltage range		Р		±3		V
Input offset voltage		Р		1	10	mV
Output offset voltage		Р		2	20	mV
Input bias current, non-inverting input		Р		5	10	μΑ
Input resistance		Р	1.5	2	6.5	МΩ
Output voltage swing	I _{OUT} = 40mA	Р		±3		V
Output drive current	V _{IN} = 3V	Р	40			mA
Positive PSRR	$\Delta V + = \pm 0.25$	Р	49	57		dB
Negative PSRR	ΔV - = ±0.25	Р	49	57		dB

Test - P = production tested. C = characterized

AC electrical characteristics (±5V, R_f = 470 Ω , G = 2, C_L = 10pF, T_A = 25°C, unless otherwise stated)

Parameter		Conditions	Min	Тур	Max	Unit
D) 4 /	D 1 111 0 1D	$V_{OUT} = 0.2V_{PP} G = +2, R_F = 470\Omega$		210		D 4111
BW ₋₃	Bandwidth, -3dB	$V_{OUT} = 0.2V_{PP}$ G = +1, R _F = 820 Ω		210		MHz
BW _{0.1}	Bandwidth, ±0.1dB	$V_{OUT} = 0.2V_{PP}$		30		MHz
SR	Slew Rate	$V_{OUT} = 2V_{PP} G = +2, R_F = 470\Omega$		600		
		$V_{OUT} = 2V_{PP} G = +1, R_F = 820\Omega$		380		V/μs
t _r	Rise time	11/ 100/ 000/		5.8		
t _f	Fall time	V _{OUT} = ±1V, 10% - 90%		4.6		ns
t _p	Propagation delay	V _{OUT} = ±2V, 10% - 90%		2.6		
dG	Differential phase, NTSC	NTSC/PAL, 280mV _{PP}		0.04		%
dP	Differential phase, NTSC	DC = -1.428V to +1.428 V		0.04°		

Applications information

A typical circuit application is shown in Figure 1. This is suitable for 75Ω transmission line connections at both the input and the output and is useful for distribution of wide-band signals such as video via cables. The 75Ω reverse terminating resistor R4 gives the correct matching condition to a terminated video cable. The amplifier load is then 150Ω in parallel with the local feedback network.

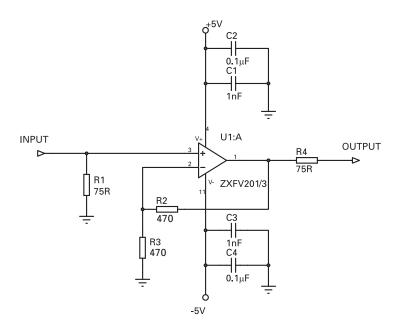


Figure 1 Typical video signal application circuit, gain = 2 (overall gain = 1 for 75 Ω load

The wide bandwidth of this device necessitates some care in the layout of the printed circuit. A continuous ground plane is required under the device and its signal connection paths, to provide the shortest possible ground return paths for signals and power supply filtering. A double-sided or multi-layer PCB construction is required, with plated-through via holes providing closely spaced low-inductance connections from some components to the continuous ground plane.

For the power supply filtering, low inductance surface mount capacitors are normally required. It has been found that very good RF decoupling is provided on each supply using a 1000pF NPO size 0805 or smaller ceramic surface mount capacitor, closest to the device pin, with an adjacent 0.1 μ F X7R capacitor. Other configurations are possible and it may be found that a single 0.01 μ F X7R capacitor on each supply gives good results. However this should be supported by larger decoupling capacitors elsewhere on the printed circuit board. Values of 1 to $10\,\mu$ F are recommended, particularly where the voltage regulators are located more than a few inches from the device. These larger capacitors are recommended to be solid tantalum electrolytic or ceramic types.

Note particularly that the inverting input of this current feedback type of amplifier is sensitive to small amounts of capacitance to ground which occur as part of the practical circuit board layout. This capacitance affects bandwidth, frequency response peaking and pulse overshoot. Therefore to minimize this capacitance, the feedback components R2 and R3 of Figure 1 should be positioned as close as possible to the inverting input connection.

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The frequency response and pulse response will vary according to particular values of resistors and layout capacitance. The response can be tailored for the application to some extent by choice of the value of feedback resistor. Figures 2 and 3 show the small signal unity gain and gain of 2 frequency responses.

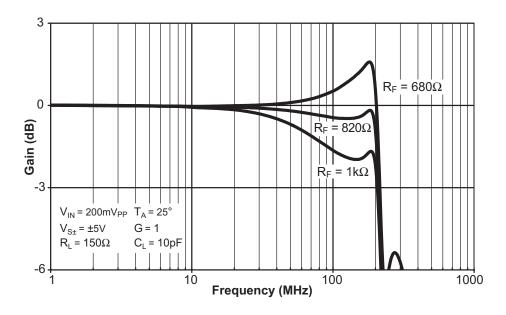


Figure 2 Unity gain small signal bandwidth

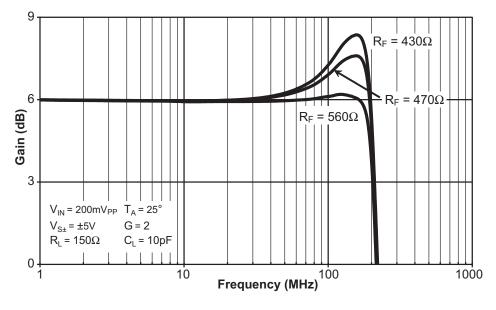
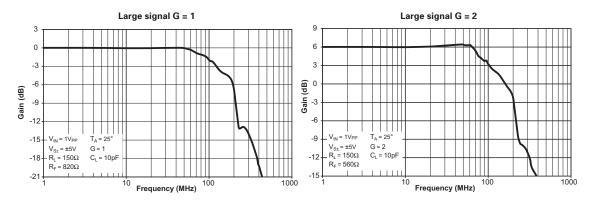


Figure 3 Gain of 2 small signal bandwidth

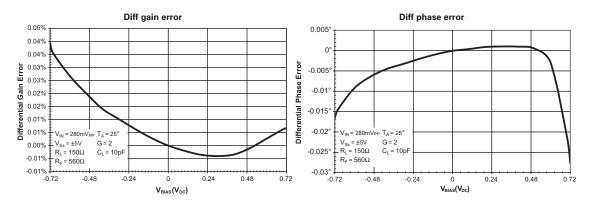
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Figures 4 and 5 show the large signal unity gain of 2 frequency responses.



Figures 4 and 5 Large signal unity gain of 2 frequency response

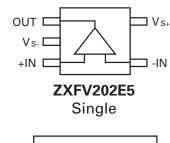
The ZXFV20x family are primarily video amplifiers; Figures 6 and 7 show the NTSC/PAL differential gain and phase errors at a gain of 2.

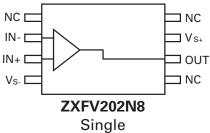


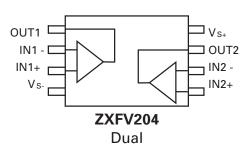
Figures 6 and 7 NTSC/PAL differential gain and phase errors at a gain of 2

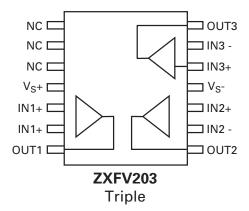
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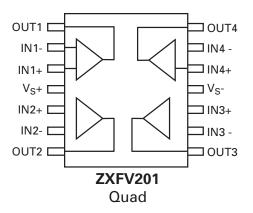
Pinout details



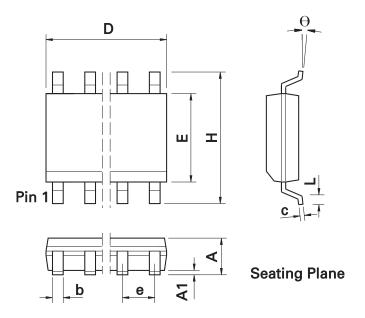








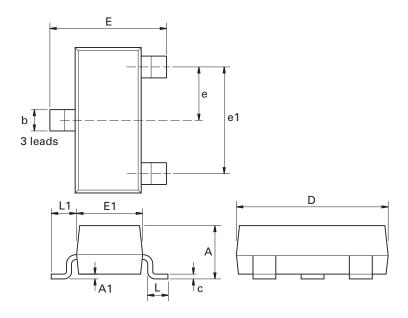
Package details - SO8, SO14



Dim.	Inc	hes	Millin	illimeters Dim. Inches Mi		Inches		Millin	neters
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
Α	0.053	0.069	1.35	1.75	L	0.016	0.050	0.40	1.27
A1	0.004	0.010	0.10	0.25	е	0.050	BSC	1.27	BSC
D (8 pin)	0.189	0.197	4.80	5.00	b	0.013	0.020	0.33	0.51
D (14 pin)	0.337	0.344	8.55	8.75	С	0.008	0.010	0.19	0.25
Н	0.228	0.244	5.80	6.20	θ	0°	8°	0°	8°
Е	0.150	0.157	3.80	4.00	h	0.010	0.020	0.25	0.50

Note: Controlling dimensions are in inches. Approximate dimensions are provided in millimeters

Package outline - SOT23



Dim.	Millimeters		Inc	Inches		Millimeters		Inc	hes
	Min.	Max.	Min.	Max.		Min.	Max.	Max.	Max.
Α	-	1.12	- 0.044 e1 1.90 NOM		1.90 NOM		0.075	NOM	
A1	0.01	0.10	0.0004	0.004	Е	2.10	2.64	0.083	0.104
b	0.30	0.50	0.012	0.020	E1	1.20	1.40	0.047	0.055
С	0.085	0.120	0.003	0.008	L	0.25	0.62	0.018	0.024
D	2.80	3.04	0.110	0.120	L1	0.45	0.62	0.018	0.024
е	0.95	NOM	0.0375	NOM	-	-	-	-	-

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